

## Guest Editorial

### *10th Electron Technology ELTE 2010 and 34th International Microelectronics and Packaging IMAPS/CPMT Poland Joint Conference*

Every year Poland Chapters of IMAPS (International Microelectronics and Packaging Society) and IEEE CPMT (Components, Packaging and Manufacturing Technology) organize international technical conferences where the matters related to *everything between chips and systems*, especially fabrication of passives and assembling problems, are presented. These annual conferences are well recognized by specialists working in the area of microelectronics and packaging because the most valuable contributions from these meetings are published in well-known international journals. For example, special sections from conferences which took place in 2004, 2005 and 2008 were published in *Microelectronics Reliability* (vol. **45**(12), 2005, vol. **48**(6), 2008, and vol. **49**(6), 2009, respectively). On the other hand, the Electron Technology ELTE conferences are Polish national conferences with general topics devoted to characterization of electronic and photonic materials, the characterization and fabrication of IC and microsystem chips. It is clearly visible that the topics of both conferences partially overlap, but also complement each other.

The Faculty of Microsystem Electronics and Photonics, Wrocław University of Technology, was honored in 2010 to host both these conferences. Therefore, based on the reason given above, the organizers decided to join the 10th Electron Technology ELTE Conference with the 34th International Microelectronics and Packaging IMAPS-CPMT Poland Conference. This joint conference took place in Wrocław, the capital of Lower Silesia, one of the oldest and most beautiful cities in Poland, but also one of the most dynamically developing ones, between 22 and 25 September 2010, at the premises of Wrocław University of Technology. The event was held by the Faculty of Microsystem Electronics and Photonics of Wrocław University of Technology, in cooperation with IMAPS Poland Chapter, IEEE CPMT Poland Chapter and Committee of Electronics and Telecommunication of the Polish Academy of Sciences. The conference was a part of celebrations connected with 100 years of higher technical education in Wrocław.

The conference, accomplished by the small table top exhibition, was attended by 220 participants from all Polish scientific institutions involved in electronic and packaging technologies as well as specialists from Austria, the Czech Republic,

France, Germany, Great Britain, Ireland, Sweden, Switzerland and the United States. During the conference 6 plenary invited lectures and 58 session ones were delivered. Moreover, 149 poster presentations took place.

In this special issue of *Optica Applicata*, we collected twenty eight papers, covering the broad range of the conference scope. All of them were subjected to the journal's regular reviewing procedure. The first six papers (SZYSZKAET *et al.*, CZERWOSZ *et al.*, PISKORSKI *et al.*, RAMIĄCZEK-KRASOWSKA *et al.*, SERAFIŃCZUK *et al.* and SKWIERCZYŃSKI *et al.*) are related to micro- and nanoelectronics. The next six papers (prepared by PIOTROWSKI *et al.*, ZNAMIROWSKI, KARASIŃSKI *et al.*, KOZŁOWSKA *et al.*, SANKOWSKA *et al.* and SIBIŃSKI *et al.*) present various matters of modern photonics. Subsequent seven papers (GOLONKA *et al.*, GRZEBYK *et al.*, SZCZYPIŃSKI *et al.*, GRZELKA *et al.*, KUBICKI *et al.*, ŚNIADEK *et al.* and ZUBEL *et al.*) describe various matters connected with fabrication and characterization of microsystems. Problems related to electronics materials are contained in five papers (GUZIEWICZ *et al.*, DOMANIEWSKA *et al.*, KOŁODZIEJ *et al.*, MLECZKO *et al.* and SIERADZKA *et al.*). Finally, the last four papers in this issue, prepared by BEMBNOWICZ *et al.*, MROCZKOWSKI *et al.*, SWATOWSKA *et al.* as well as TADASZAK *et al.*, are focused on the properties of modern hybrid technologies.

We hope that this special issue will appeal to *Optica Applicata* readers and will help to understand the modern scientific and technical problems existing in electronics both in chips and between the chips and the systems. We hope the readers will find it useful in their work, finding new solutions or expanding horizons of their knowledge. Last but not least, we would like to thank all the authors and the reviewers for their valuable contribution.

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